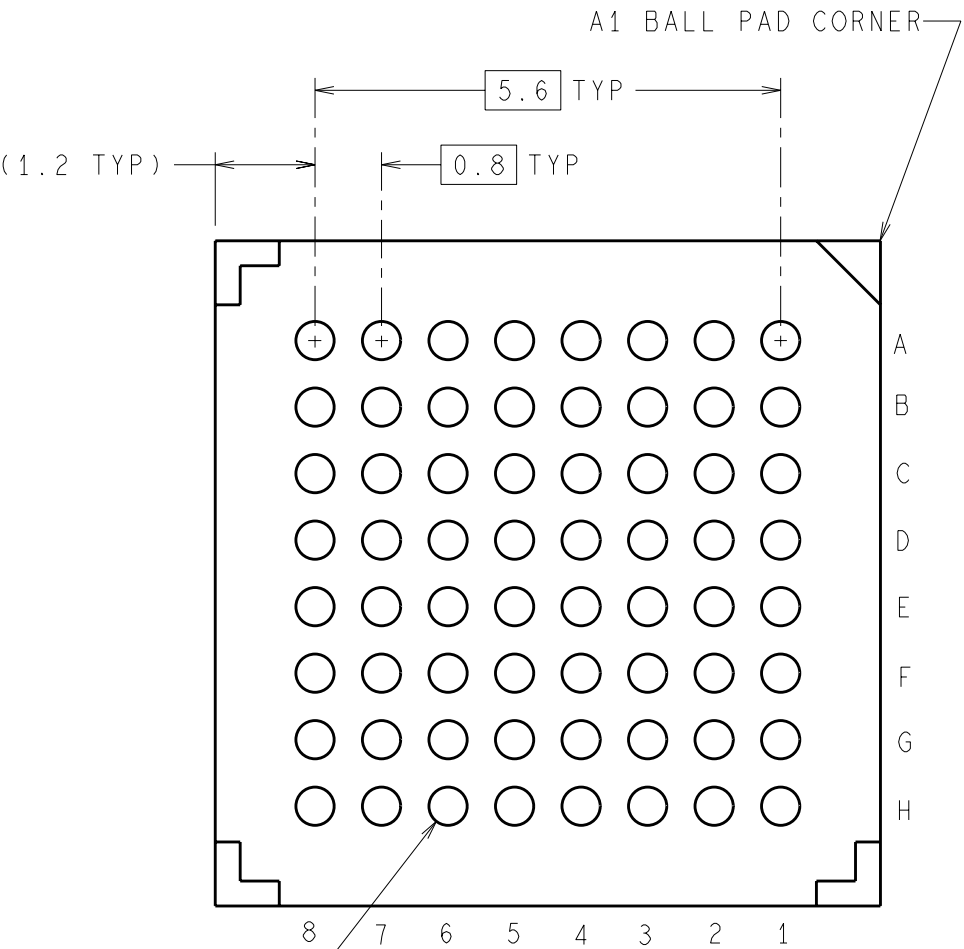
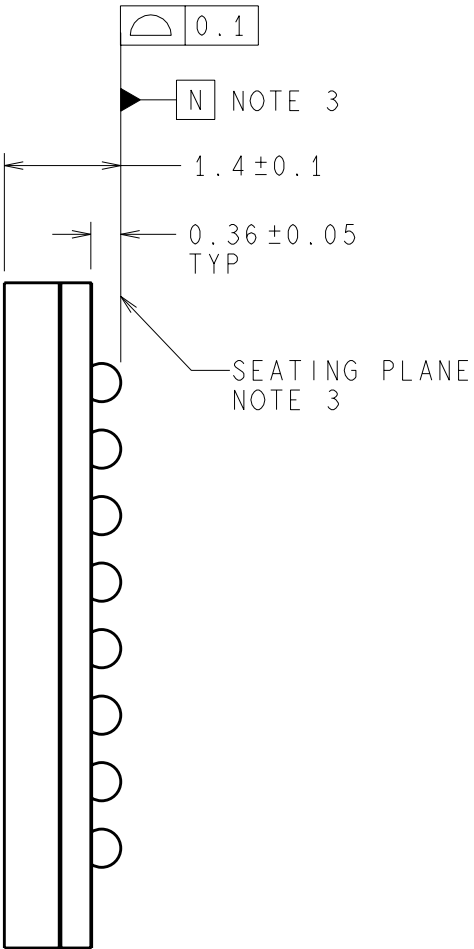
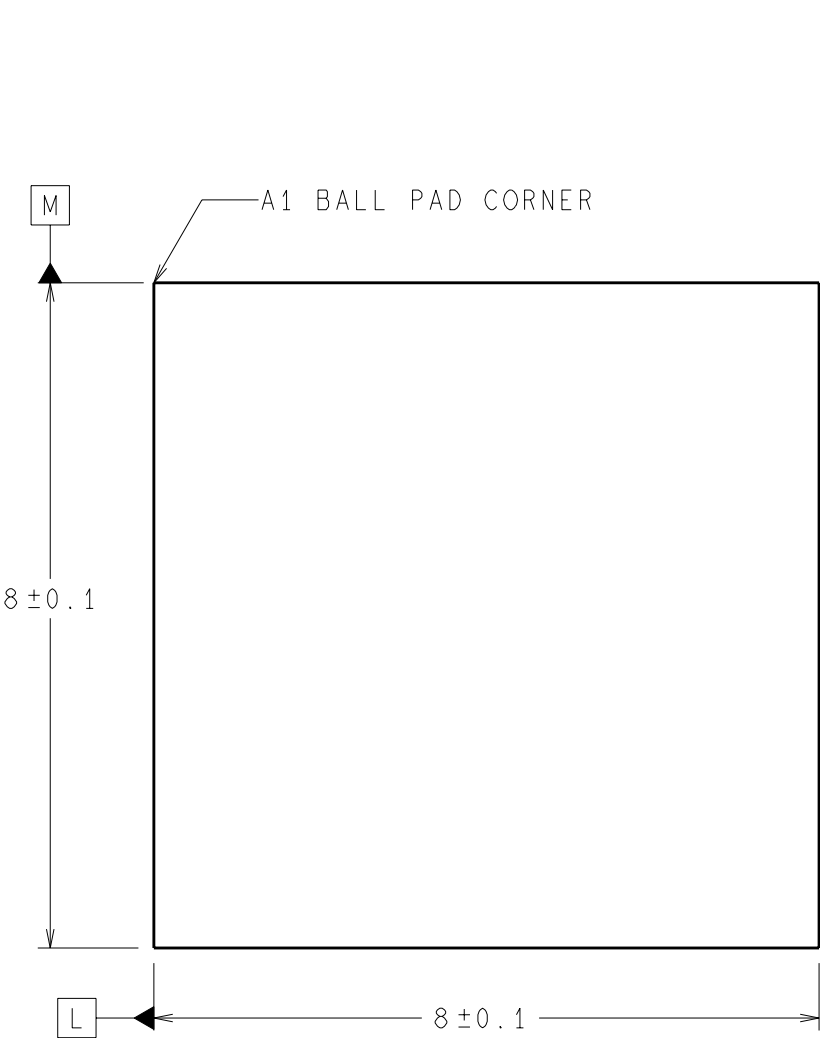


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11990	05/08/1998	TL/SL
B	REVISE TITLE	12174	03/18/1999	MS/AT
C	UPDATE PKG CORNERS & NOTE 4; CHANGE DWG FORMAT TO B SIZE	908	01/15/2003	TL/AT



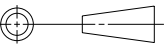
64X $\varnothing 0.46$				
$\varnothing 0.15$ (M)	N	L	S	M
$\varnothing 0.08$ (M)	N			

NOTE 2

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- NO JEDEC REGISTRATION AS OF JANUARY 2003.

DIMENSIONS ARE IN MILLIMETERS

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG		05/08/1998		
DFTG. CHK.	MARTA SUCHY		01/15/2003		
ENGR. CHK.	ANNY TU		01/15/2003		
				FBGA, PLASTIC, LAMINATED, 8 x 8 x 1.4mm, 64 BALL, 0.8mm PITCH	
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		NTS	B	(SC)MKT-SLC64A	C
FORMERLY: N/A				SHEET 1 of 1	